

Title (en)

LOW-ADHESION MATERIAL, MOLDS FOR MOLDING RESINS, AND STAINPROOF MATERIAL

Title (de)

GERING KLEBENDES MATERIAL, HARZFORMUNGSFORM UND FLECKENRESISTENTES MATERIAL

Title (fr)

MATERIAU DE FAIBLE ADHESION, MOULES POUR LE MOULAGE DE RESINES ET MATERIAU ANTITACHE

Publication

EP 1978005 A4 20110525 (EN)

Application

EP 06843407 A 20061227

Priority

- JP 2006326025 W 20061227
- JP 2006017335 A 20060126

Abstract (en)

[origin: EP1978005A1] A resin molding die (1) has a molding surface (6) formed of a low adhesion material (3) formed of a solid solution of La- Y 2 O 3 produced from Y 2 O 3 and an other oxide of La 2 O 3 . La 2 O 3 contains La, which has an ionic radius larger than Y 3+ , and is larger in basicity than Y 2 O 3 . The low adhesion material (3) contains La 2 O 3 at a predetermined ratio relative to a total of Y 2 O 3 and La 2 O 3 . The low adhesion material (3) thus has a large ionic radius contributing to a smaller number of sites per unit area than Y 2 O 3 , a larger basicity contributing to a smaller force binding the low adhesion material with a basic substance than Y 2 O 3 , and a ratio contributing to shape retention. The low adhesion material (3) thus less adhesive and more shape-retentive than Y 2 O 3 configures the molding surface (6). A low adhesion material that is less adhesive to a basic substance than Y 2 O 3 is and excellently shape-retentive, and an excellently releasable and shape-retentive resin molding die can thus be obtained.

IPC 8 full level

C04B 35/50 (2006.01); **B29C 33/38** (2006.01)

CPC (source: EP KR US)

B29C 33/38 (2013.01 - KR); **B29C 33/56** (2013.01 - EP US); **B29C 33/60** (2013.01 - EP US); **C04B 35/50** (2013.01 - EP KR US); **C04B 35/505** (2013.01 - EP US); **C04B 35/645** (2013.01 - EP US); **C04B 2235/3213** (2013.01 - EP US); **C04B 2235/3225** (2013.01 - EP US); **C04B 2235/3227** (2013.01 - EP US)

Citation (search report)

- [X] GB 1153757 A 19690529 - COMBUSTIBLE NUCLEAIRE [FR]
- [X] JP H0732445 A 19950203 - SHINAGAWA REFRACTORIES CO
- [X] EP 0204674 A2 19861210 - REMET CORP [US]
- See references of WO 2007086228A1

Designated contracting state (EPC)

NL

DOCDB simple family (publication)

EP 1978005 A1 20081008; **EP 1978005 A4 20110525**; CN 101238081 A 20080806; JP 2007197251 A 20070809; JP 3974152 B2 20070912; KR 100961798 B1 20100608; KR 20080015803 A 20080220; KR 20090082293 A 20090729; TW 200730467 A 20070816; TW I339198 B 20110321; US 2008296532 A1 20081204; WO 2007086228 A1 20070802

DOCDB simple family (application)

EP 06843407 A 20061227; CN 200680029022 A 20061227; JP 2006017335 A 20060126; JP 2006326025 W 20061227; KR 20077027278 A 20061227; KR 20097013884 A 20061227; TW 95150108 A 20061229; US 92042106 A 20061227